



N- and P-Channel 20-V (D-S) MOSFET

PRODUCT SUMMARY							
	V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)				
N-Channel	20	0.0145 at V _{GS} = 10 V	9.6				
	20	0.017 at V _{GS} = 4.5 V	8.6				
P-Channel	- 20	0.033 at $V_{GS} = -4.5 \text{ V}$	- 6.2				
	- 20	0.050 at V _{GS} = - 2.5 V	- 5				

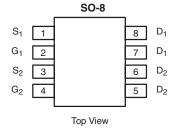
FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET[®] Power MOSFET
- · Compliant to RoHS directive 2002/95/EC



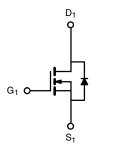
APPLICATIONS

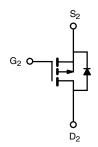
- Level Shift
- · Load Switch



Ordering Information: Si4511DY-T1-E3 (Lead (Pb)-free)

Si4511DY-T1-GE3 (Lead (Pb)-free and Halogen-free)





ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted								
Parameter			N-	N-Channel		P-Channel		
		Symbol	10 s	Steady State	10 s	Steady State	Unit	
Drain-Source Voltage		V_{DS}	20		- 20		V	
Gate-Source Voltage		V _{GS}		± 16	± 12		V	
Continuous Drain Current /T 150 °C\a.b	T _A = 25 °C	1-	9.6	7.2	- 6.2	- 4.6		
Continuous Drain Current $(T_J = 150 ^{\circ}C)^{a, b}$	T _A = 70 °C	ΙD	7.7	5.8	- 4.9	- 3.7	Α	
Pulsed Drain Current		I _{DM}		40	- 40		^	
Continuous Source Current (Diode Conduction) ^a		I _S	1.7	0.9	- 1.7	- 0.9		
Mariana Barra Birainatian 8	T _A = 25 °C	P _D	2	1.1	2	1.1	W	
Maximum Power Dissipation ^a	T _A = 70 °C	' D	1.3	0.7	1.3	0.7	VV	
Operating Junction and Storage Temperature Range		T _J , T _{stq}	- 55 to 150				°C	

THERMAL RESISTANCE RATINGS								
			N-Ch	annel	P-Channel			
Parameter		Symbol	Тур.	Max.	Тур.	Max.	Unit	
Maximum Junction-to-Ambient ^a	t ≤ 10 s	R _{thJA}	50	62.5	50	62.5		
	Steady State	' 'thJA	85	110	90	110	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R _{thJF}	30	40	30	35		

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

b. $t \le 10 \text{ s}$.



SPECIFICATIONS T _J = 25 °C, unless otherwise noted									
Parameter	Symbol	Test Conditions		Min.	Тур.	Max.	Unit		
Static	T		T		ı				
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	N-Ch	0.6		1.8	V		
	* GS(tn)	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	P-Ch	- 0.6		- 1.4			
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 16 \text{ V}$	N-Ch			± 100	nA		
	'655	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	P-Ch			± 100	11/2		
Zero Gate Voltage Drain Current		$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch			1			
	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch			- 1	^		
Zero Gate Voltage Drain Current	טטי	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	N-Ch			5	μΑ		
		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$	P-Ch			- 5			
On-State Drain Current ^b		$V_{DS} = 5 \text{ V}, V_{GS} = 10 \text{ V}$	N-Ch	40			А		
	I _{D(on)}	$V_{DS} = -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	- 40					
Drain-Source On-State Resistance ^b	R _{DS(on)}	V _{GS} = 10 V, I _D = 9.6 A	N-Ch		0.0115	0.0145	Ω		
		V _{GS} = - 4.5 V, I _D = - 6.2 A	P-Ch		0.022	0.033			
		V _{GS} = 4.5 V, I _D = 8.6 A	N-Ch		0.0135	0.017			
		V _{GS} = - 2.5 V, I _D = - 5 A	P-Ch		0.035	0.050			
Forward Transconductance ^b	~	V _{DS} = 15 V, I _D = 9.6 A	N-Ch		33		0		
	9 _{fs}	V _{DS} = - 15 V, I _D = - 6.2 A	P-Ch		17		S		
h	V _{SD}	I _S = 1.7 A, V _{GS} = 0 V	N-Ch		0.8	1.2	.,		
Diode Forward Voltag ^b		I _S = - 1.7 A, V _{GS} = 0 V	P-Ch		- 0.8	- 1.2	V		
Dynamic ^a									
Total Cata Charge	Qg		N-Ch		11.5	18			
Total Gate Charge		N-Channel $V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 9.6 \text{ A}$	P-Ch		17	20	nC		
Gate-Source Charge	Q_{gs}	$v_{DS} = 10 \text{ V}, v_{GS} = 4.5 \text{ V}, I_D = 9.6 \text{ A}$	N-Ch		3.7				
	ys	P-Channel P-C			4.1				
Gate-Drain Charge	Q_{qd}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6.2 \text{ A}$	N-Ch		3.3				
	3.		P-Ch		4.3	20			
Turn-On Delay Time Rise Time	t _{d(on)}	N-Channel $V_{DD} = 10 \text{ V, } R_L = 10 \ \Omega$ $I_D \cong 1 \text{ A, } V_{GEN} = 10 \text{ V, } R_g = 6 \ \Omega$	N-Ch P-Ch		12 25	20 40			
			N-Ch		12	20	_		
			P-Ch		30	45			
Turn Off Dalay Tim		P-Channel	N-Ch		55	85			
Turn-Off Delay Time	t _{d(off)}	$V_{DD} = -10 \text{ V}, R_L = 10 \Omega$	P-Ch		70	105	ns		
Fall Time	t _f	$I_D \cong -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_q = 6 \Omega$	N-Ch		15	25			
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Source-Drain Reverse Recovery Time	t _{rr}	$I_F = 1.7 \text{ A}, dI/dt = 100 \text{ A/}\mu\text{s}$	N-Ch		50	100			
Source-Diam neverse necovery Time	۲rr	I _F = - 1.7 A, dI/dt = 100 A/μs	P-Ch		40	80			

Notes:

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Guaranteed by design, not subject to production testing.

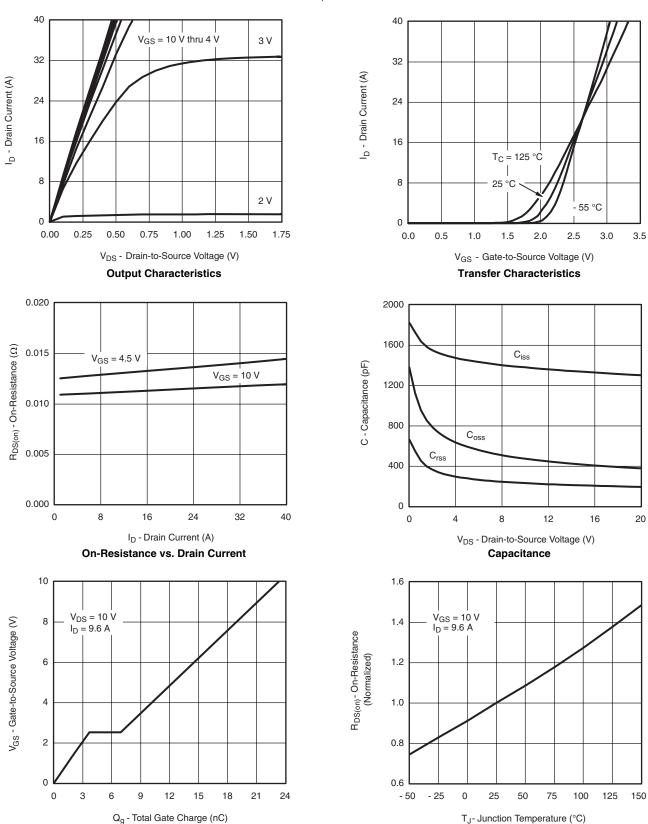
b. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %.







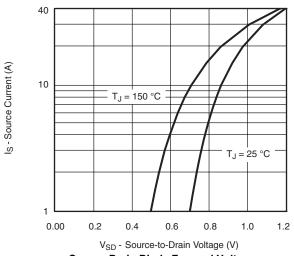
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



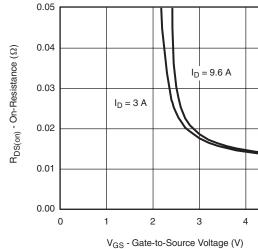
Gate Charge

On-Resistance vs. Junction Temperature

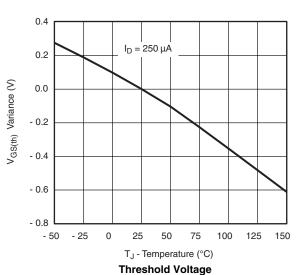
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

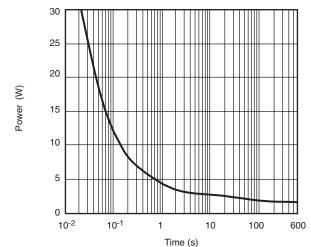


Source-Drain Diode Forward Voltage

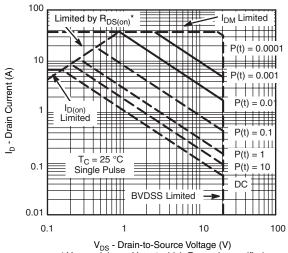


On-Resistance vs. Gate-to-Source Voltage





Single Pulse Power

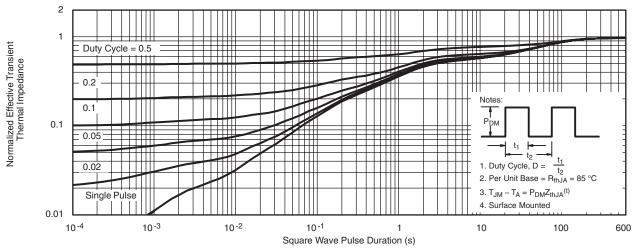


 $\label{eq:VDS} V_{DS} \text{ - Drain-to-Source Voltage (V)} \\ \text{* } V_{DS} \text{ > minimum } V_{GS} \text{ at which } R_{DS(on)} \text{ is specified}$

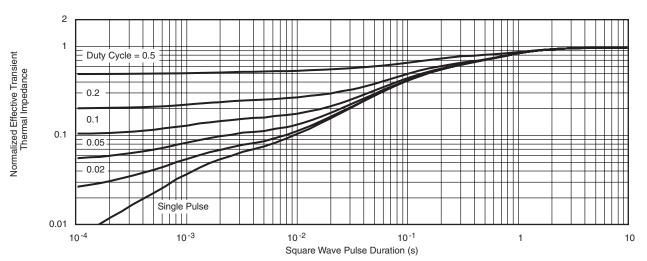
Safe Operating Area



N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



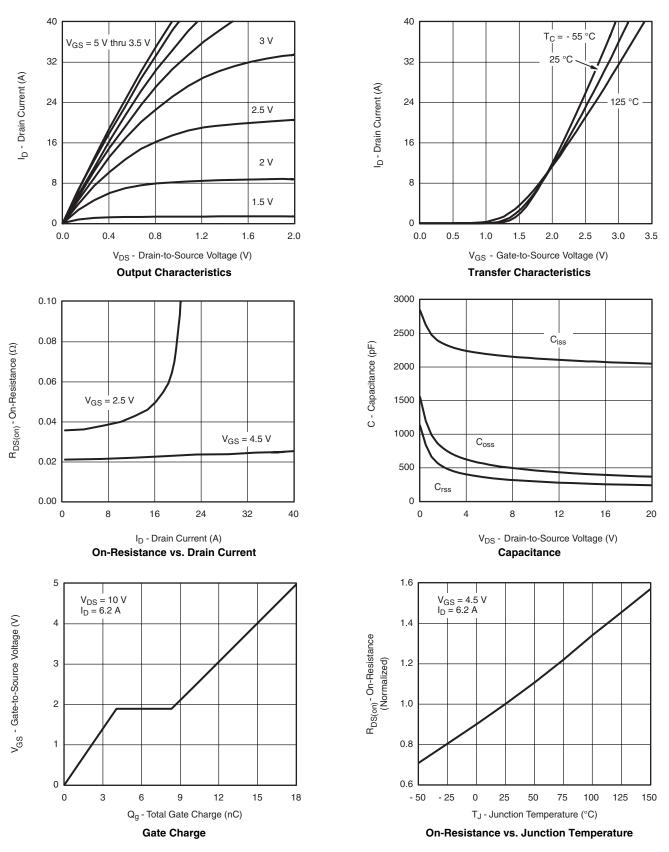
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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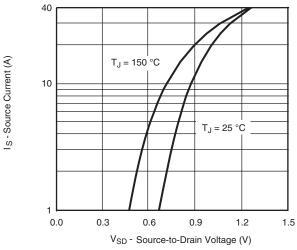
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

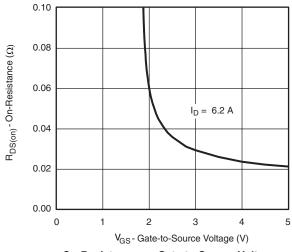






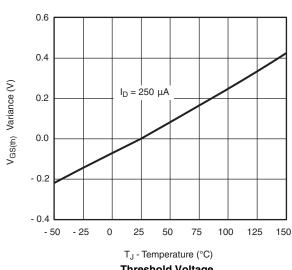
P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

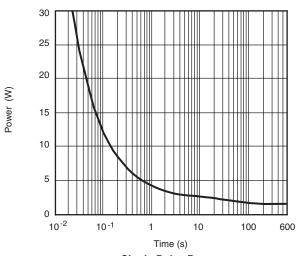




Source-Drain Diode Forward Voltage

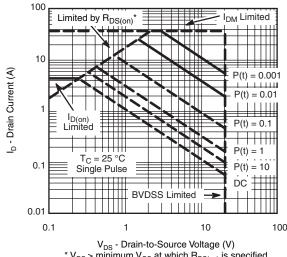






Threshold Voltage

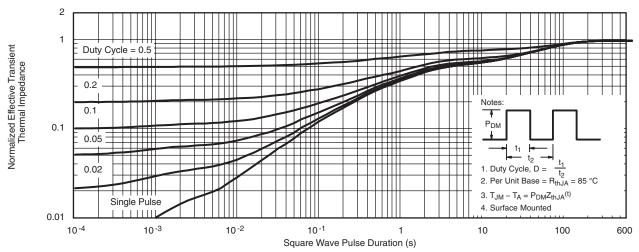
Single Pulse Power



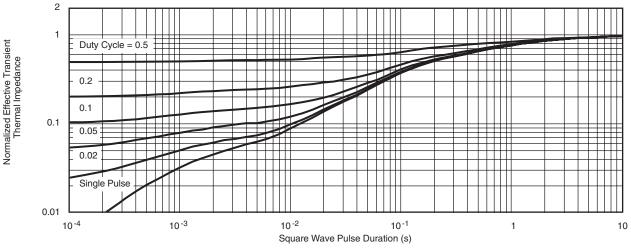
* V_{DS} > minimum V_{GS} at which $R_{DS(on)}$ is specified Safe Operating Area



P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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